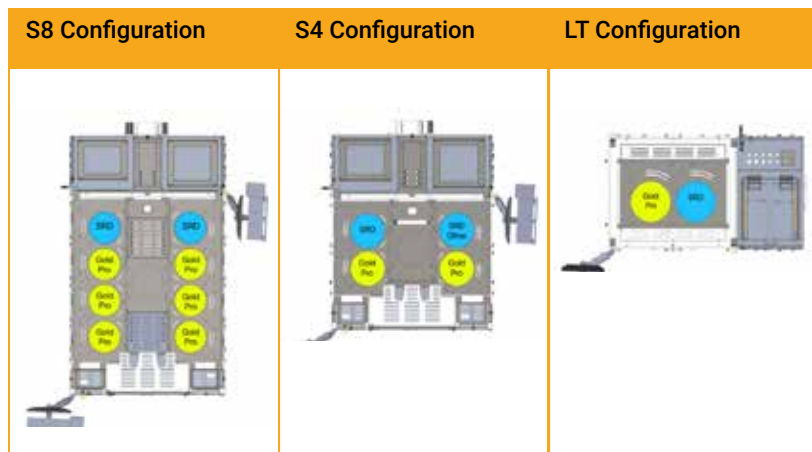


Solstice® GoldPro™ Gold Electroplating System

No Compromise: Plating Rate and Uniformity Performance Results

Our Solstice® GoldPro™ electrochemical deposition plating system are designed to deliver efficiency, speed, and improved cost of ownership to your process. The system leverages our proprietary fluid flow and electric field shaping design to give you high plating rates and uniform depositions every time.

In addition, plating reactors can be supplied with chemistry via individual tanks or shared for chamber matching. Nitrogen protection is offered in the bath and in the plating reactor to minimize bath oxidation and extend your bath life. Our GoldPro technology is further differentiated by its ability to plate highly uniform features without the added complexity of using paddles or agitators.



Solstice configurations with multiple chambers can be paired with one or more SRD chambers.



Key Applications

Leading manufacturers of GaAs and GaN devices are choosing Solstice GoldPro as their plating technology for applications from RF to VCSELs and microLEDs.

Features

- Advanced fluidics and electric field control
- Nitrogen bath life protection
- Bath analysis integration
- Automated and programmable dosing

Parameter	GoldPro
Within Feature Uniformity	<1.5%
Within Die Uniformity	<1%
Within Wafer Uniformity	<3%
Wafer to Wafer Uniformity	<4%
Step Coverage	>90%
Feature Size	<1 micron wide
Plating Overburden	<1 micron